

Title (en)

METHOD FOR THE PRODUCTION OF STRUCTURED, ELECTRICALLY CONDUCTIVE SURFACES

Title (de)

VERFAHREN ZUR HERSTELLUNG STRUKTURIERTER, ELEKTRISCH LEITFÄHIGER OBERFLÄCHEN

Title (fr)

PROCÉDÉ DE FABRICATION DE SURFACES STRUCTURÉES ÉLECTRO-CONDUCTRICES

Publication

EP 2127507 A1 20091202 (DE)

Application

EP 08701541 A 20080117

Priority

- EP 2008050479 W 20080117
- EP 07100832 A 20070119
- EP 08701541 A 20080117

Abstract (en)

[origin: WO2008087172A1] Disclosed is a method for producing structured, electrically conductive surfaces on a substrate. Said method comprises the following steps: a) a base layer containing particles that can be coated in an electroless manner and/or be electro-plated is structured on the substrate by removing the base layer according to a predefined structure with the help of a laser; b) the surface of the particles that can be coated in an electroless manner and/or be electro-plated is activated; and c) an electrically conductive coating is applied to the structured base layer.

IPC 8 full level

H05K 1/09 (2006.01); **H05K 3/02** (2006.01)

CPC (source: EP KR US)

H05K 3/02 (2013.01 - KR); **H05K 3/027** (2013.01 - EP US); **H05K 3/185** (2013.01 - EP US); **H05K 3/246** (2013.01 - EP US); **H05K 1/092** (2013.01 - EP US); **H05K 1/095** (2013.01 - EP US); **H05K 2201/0112** (2013.01 - EP US); **H05K 2201/0347** (2013.01 - EP US); **H05K 2203/107** (2013.01 - EP US)

Citation (search report)

See references of WO 2008087172A1

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MT NL NO PL PT RO SE SI SK TR

DOCDB simple family (publication)

WO 2008087172 A1 20080724; BR PI0806629 A2 20110913; CA 2675033 A1 20080724; CN 101584258 A 20091118; EP 2127507 A1 20091202; IL 199769 A0 20100415; JP 2010517256 A 20100520; KR 20090103949 A 20091001; RU 2009131220 A 20110227; TW 200845845 A 20081116; US 2010009094 A1 20100114

DOCDB simple family (application)

EP 2008050479 W 20080117; BR PI0806629 A 20080117; CA 2675033 A 20080117; CN 200880002616 A 20080117; EP 08701541 A 20080117; IL 19976909 A 20090709; JP 2009545921 A 20080117; KR 20097017245 A 20080117; RU 2009131220 A 20080117; TW 97102105 A 20080118; US 52367208 A 20080117